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(12) **United States Design Patent**
Feng

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(54) **LIGHT EMITTING DIODE CHIP**
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(73) Assignee: **Formosa Epitaxy Incorporation,**
Taoyuan (TW)
(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

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(58) **Field of Classification Search**
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D25/155, 160, 163; D26/1
CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;
H01L 27/156; H01L 31/02; H01L 33/000079;
H01L 33/04; H01L 33/08; H01L 33/10;
H01L 33/20; H01L 33/38; H01L 33/42;
H01L 33/44; H01L 33/48; H01L 33/483;
H01L 33/486; H01L 24/06; H01J 3/021;
H01S 5/34; F21K 9/00; F21K 9/30; F21K
9/54; B82Y 20/00; B82Y 40/00
See application file for complete search history.

(57) **CLAIM**

The ornamental design for a light emitting diode chip, as shown and described.

DESCRIPTION

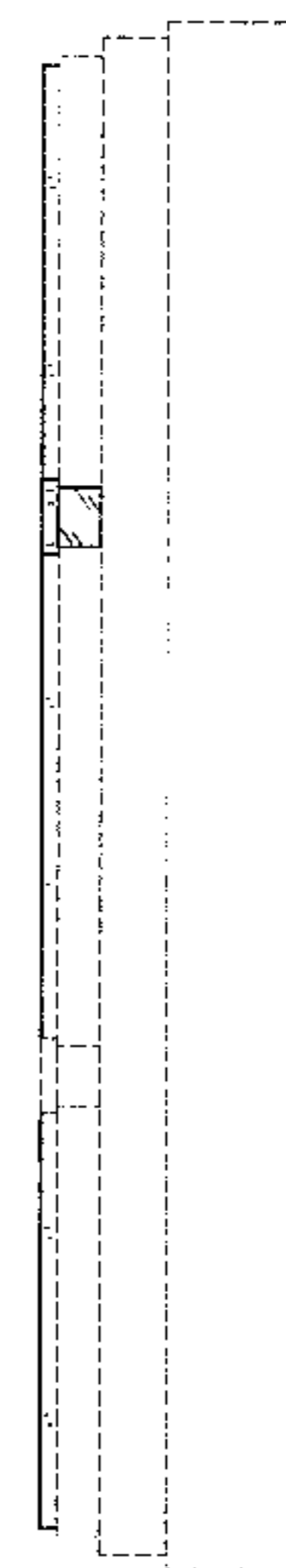
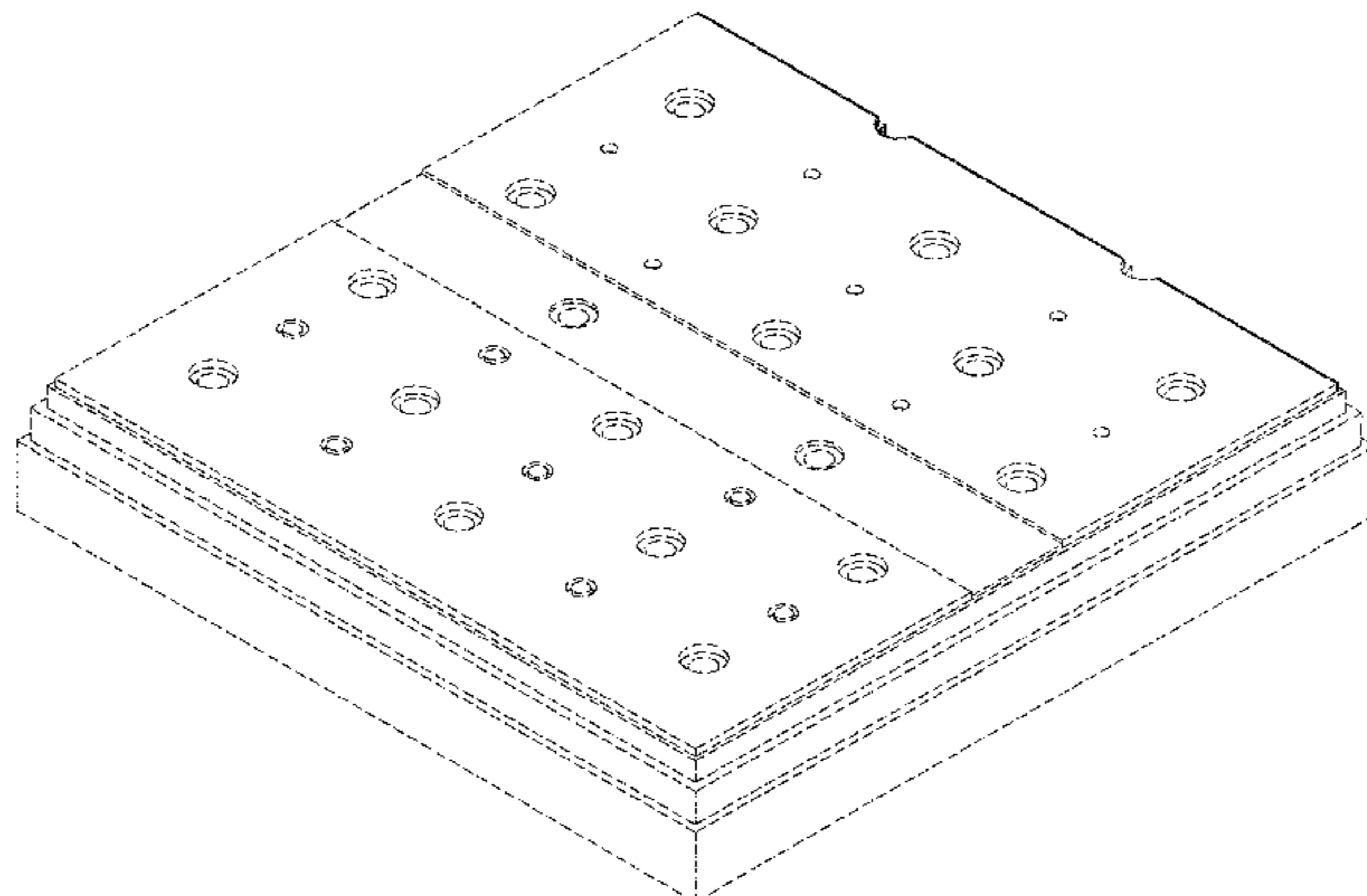
FIG. 1 is a perspective view of a light emitting diode chip showing an embodiment of my new design; FIG. 2 is a front view of the embodiment; FIG. 3 is a rear view of the embodiment; FIG. 4 is a left side view of the embodiment; FIG. 5 is a right side view of the embodiment; FIG. 6 is a top view of the embodiment; and, FIG. 7 is a bottom view of the embodiment. The broken line portions of the light emitting diode chip in FIGS. 1-7 represent unclaimed portions of the design and form no part thereof.

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1 Claim, 5 Drawing Sheets



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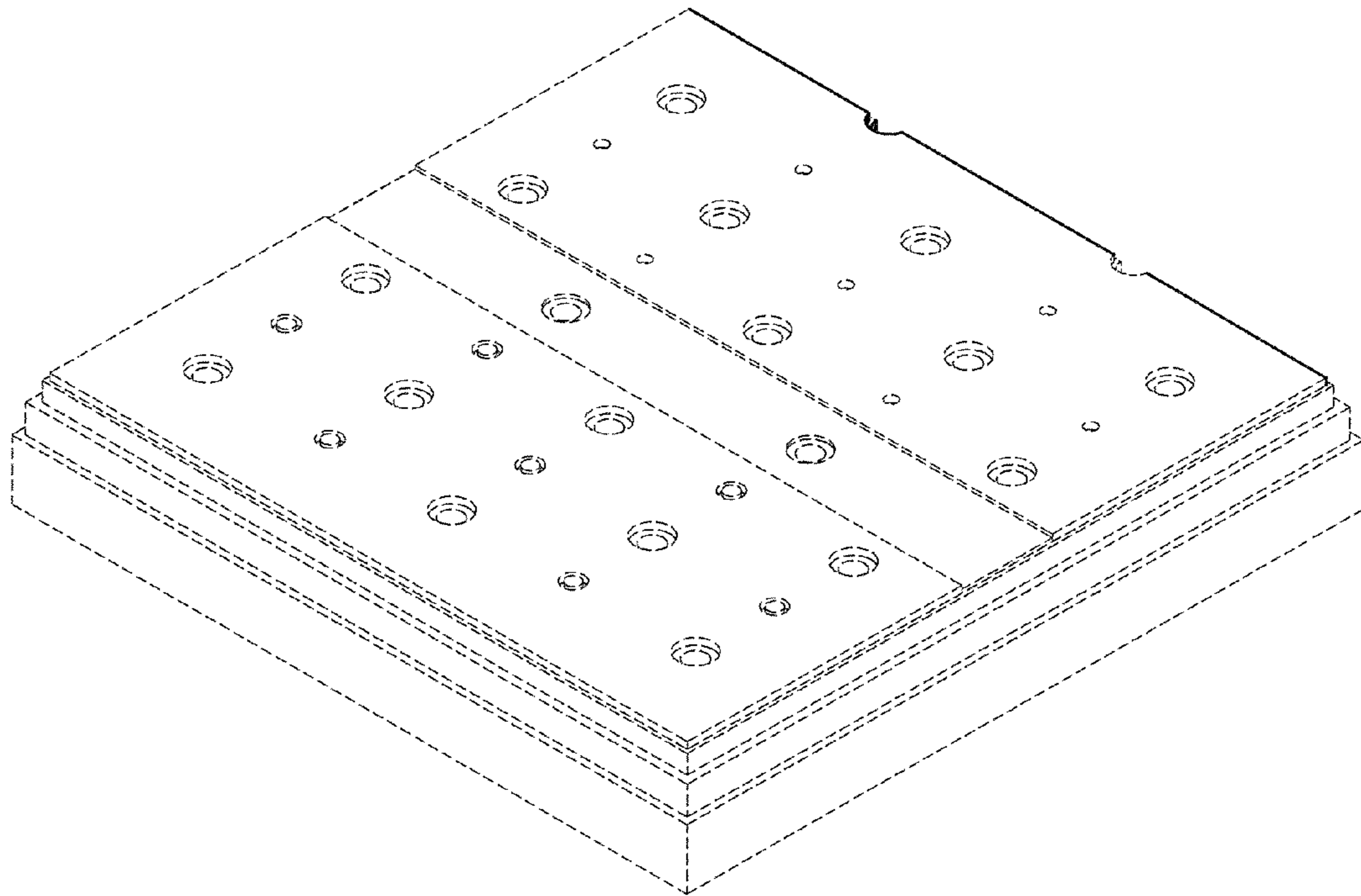


FIG. 1

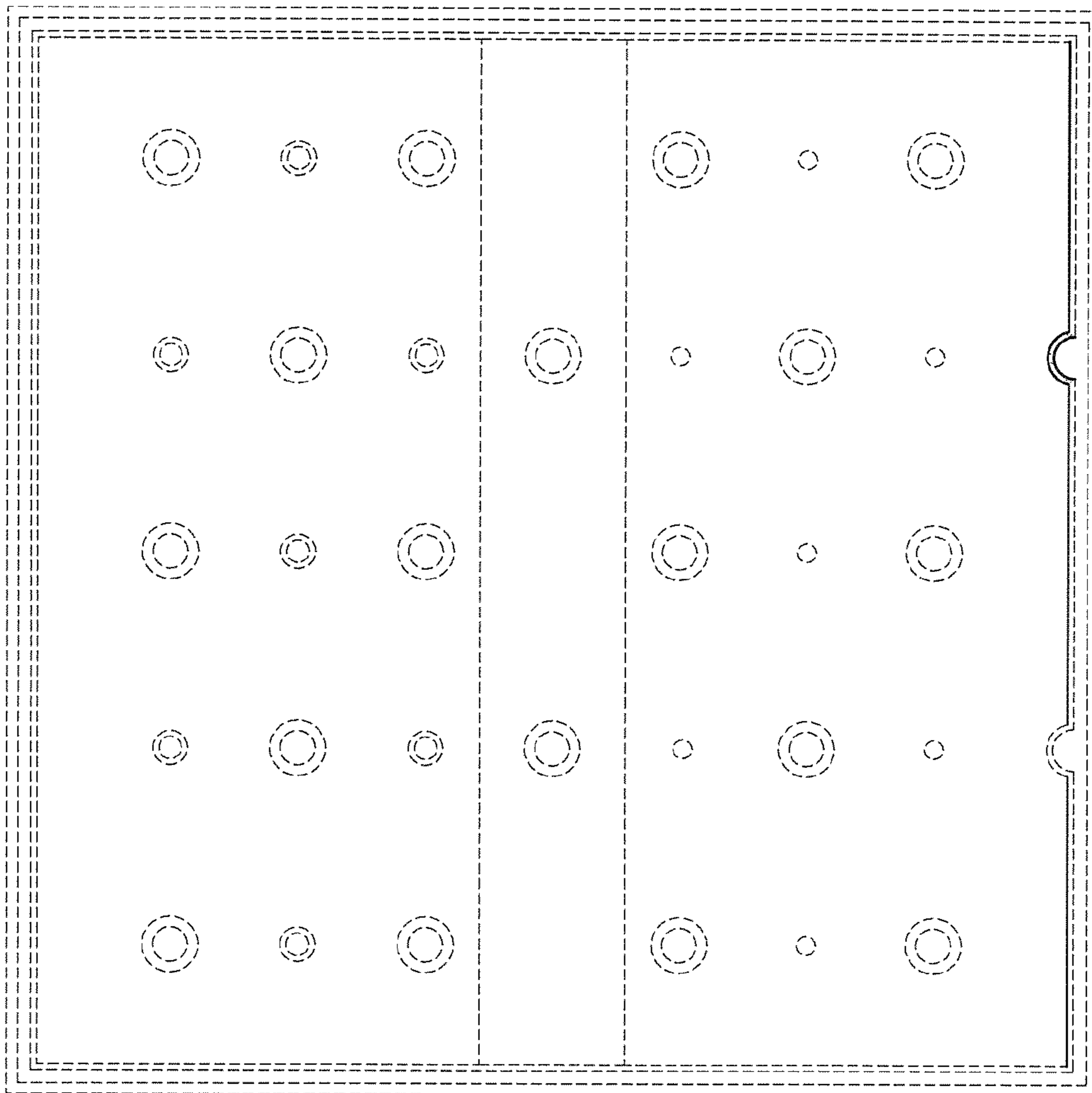


FIG. 2

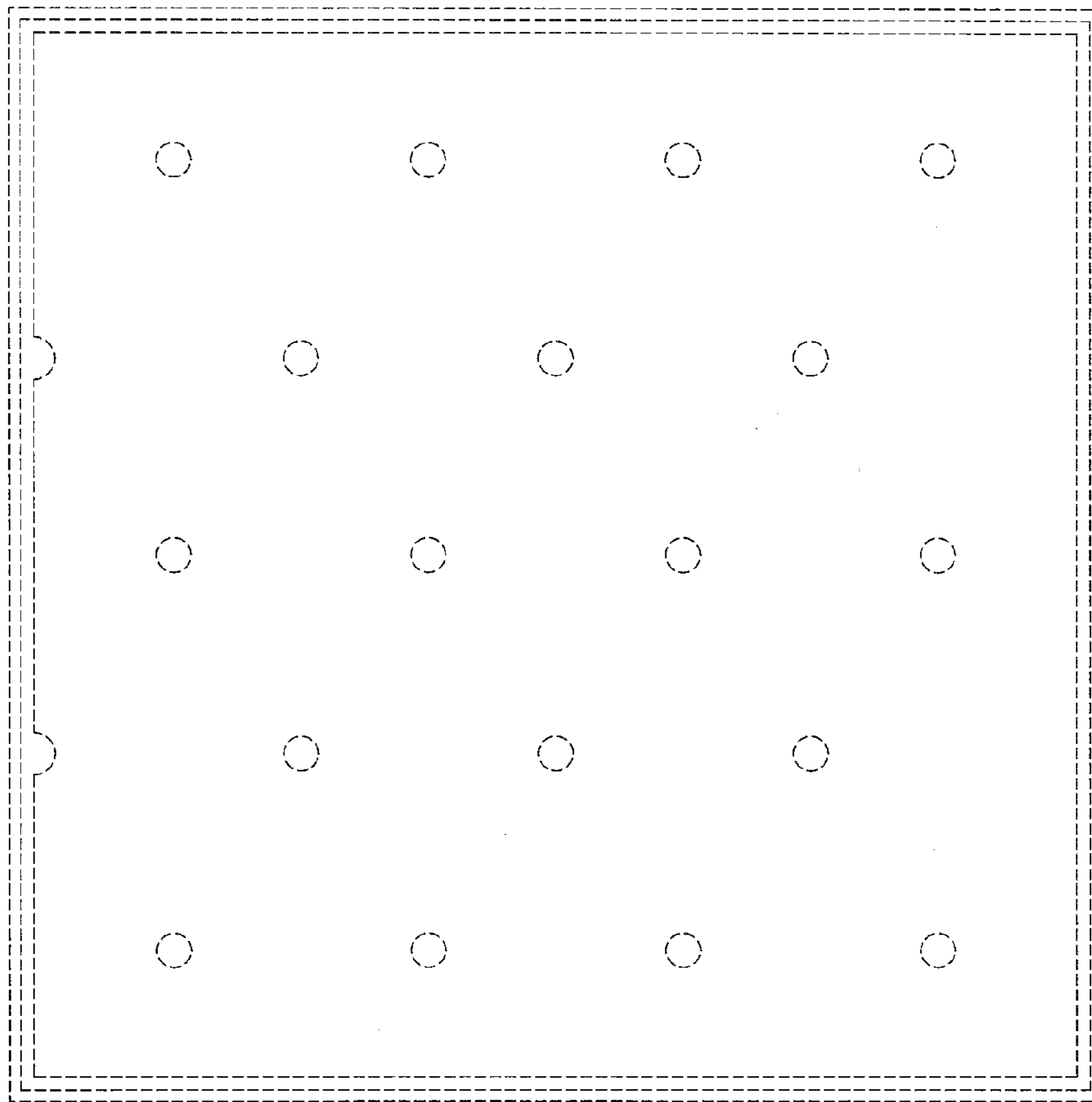


FIG. 3

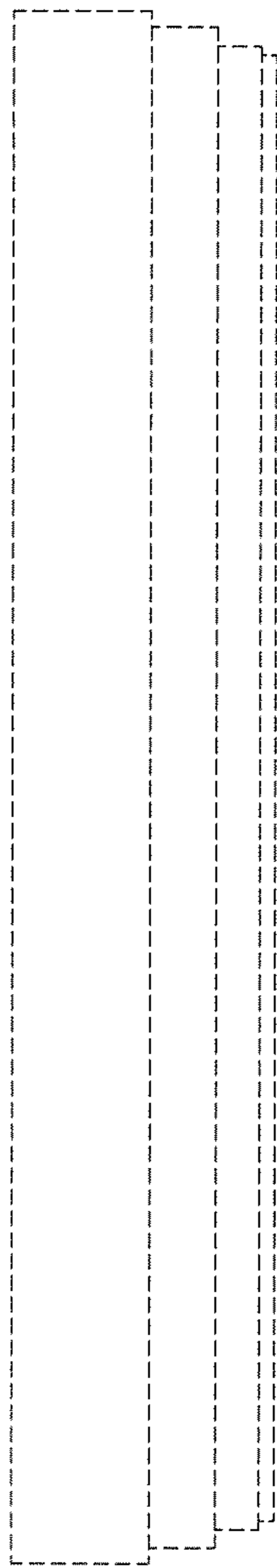


FIG. 4

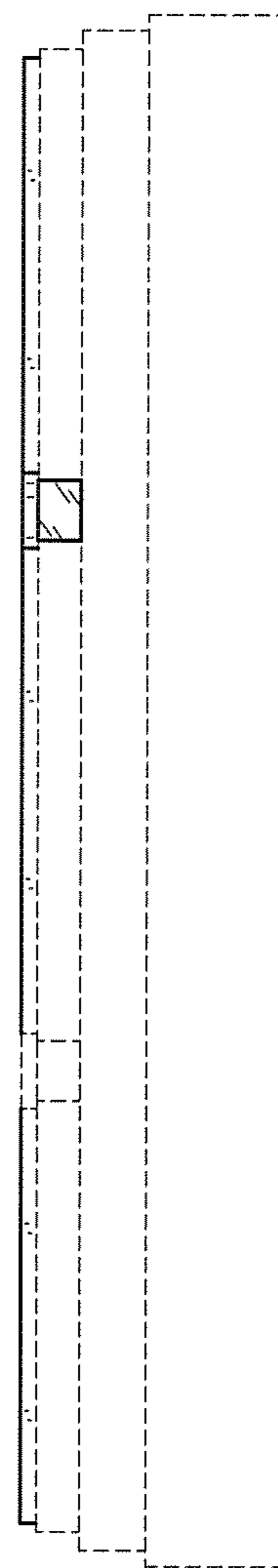


FIG. 5

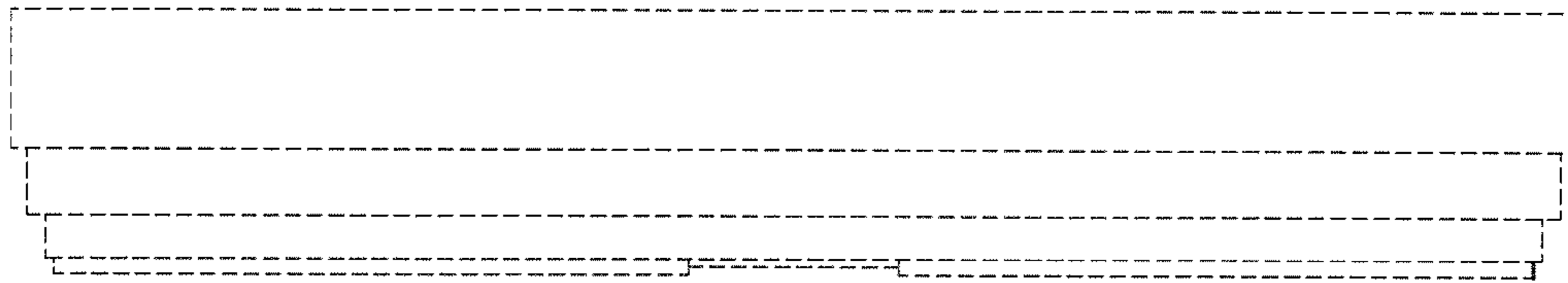


FIG. 6

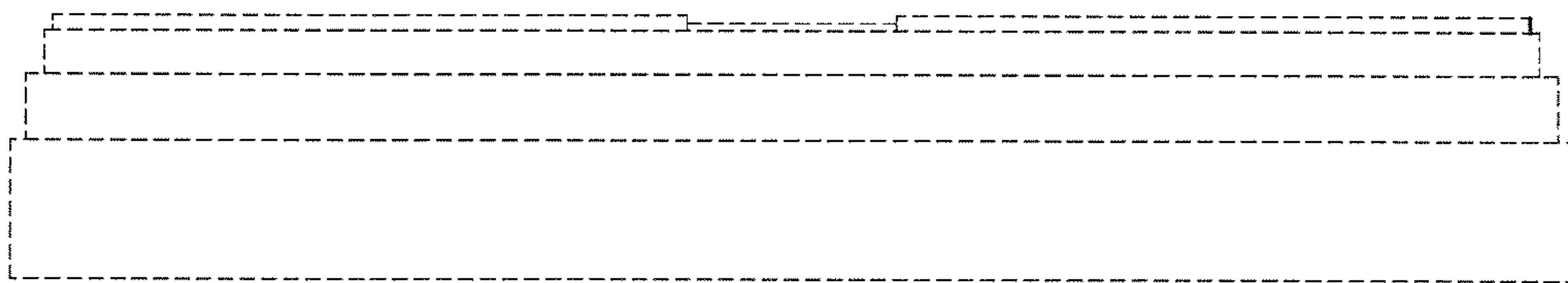


FIG. 7